

Surface Mount Schottky Power Rectifier

SMB Power Surface Mount Package

SS22T3G, SS24T3G, NRVBSS24T3G, NRVBSS24NT3G

These devices employ the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

Features

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guardring for Over-Voltage Protection
- Low Forward Voltage Drop
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable*
- These Devices are Pb-Free and are RoHS Compliant

Mechanical Characteristics

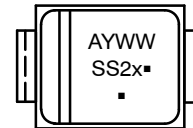
- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 95 mg (approximately)
- Cathode Polarity Band
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Available in 12 mm Tape, 2500 Units per 13 in Reel, Add "T3" Suffix to Part Number
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- ESD Ratings: Machine Model = C
Human Body Model = 3B

SCHOTTKY BARRIER RECTIFIER 2 AMPERES 20, 40 VOLTS



SMB
CASE 403A

MARKING DIAGRAM



SS2x = Specific Device Code
x = 2 or 4
A = Assembly Location**
Y = Year
WW = Work Week
▪ = Pb-Free Package

(Note: Microdot may be in either location)

**The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package, the front side assembly code may be blank.

ORDERING INFORMATION

| Device | Package | Shipping† |
|---------------|------------------|-----------------------|
| SS24T3G | SMB (Pb-Free) | 2500 / Tape & Reel |
| NRVBSS24NT3G* | SMB (Pb-Free) | 2500 / Tape & Reel |

DISCONTINUED (Note 1)

| | | |
|--------------|------------------|-----------------------|
| SS22T3G | SMB (Pb-Free) | 2500 / Tape & Reel |
| NRVBSS24T3G* | SMB (Pb-Free) | 2500 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

1. **DISCONTINUED:** These devices are not recommended for new design. Please contact your onsemi representative for information. The most current information on these devices may be available on [www.onsemi.com](#).

SS22T3G, SS24T3G, NRVBSS24T3G, NRVBSS24NT3G

MAXIMUM RATINGS

| Symbol | Rating | Value | Unit |
|---------------------------------|---|--------------------------|------------------|
| V_{RRM} V_{RWM} V_R | Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | SS22 SS24 20 40 | V |
| I_O | Average Rectified Forward Current (At Rated V_R , $T_L = 132^\circ\text{C}$) | 2.0 | A |
| I_{FRM} | Peak Repetitive Forward Current (At Rated V_R , Square Wave, 100 kHz, $T_C = 127^\circ\text{C}$) | 3.0 | A |
| I_{FSM} | Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz) | 75 | A |
| T_{stg}, T_C | Storage/Operating Case Temperature | -55 to +150 | $^\circ\text{C}$ |
| T_J | Operating Junction Temperature (Note 1) | -55 to +150 | $^\circ\text{C}$ |
| dv/dt | Voltage Rate of Change (Rated V_R , $T_J = 25^\circ\text{C}$) | 10,000 | V/ μs |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

THERMAL CHARACTERISTICS

| Symbol | Characteristic | Value | Unit |
|-----------------|---|-------|---------------------------|
| $R_{\theta JL}$ | Thermal Resistance, Junction-to-Lead (Note 2) | 24 | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient (Note 3) | 80 | |

ELECTRICAL CHARACTERISTICS

| Symbol | Characteristic | Value | | Unit |
|--------|---|--------------------------|---------------------------|------|
| | | $T_J = 25^\circ\text{C}$ | $T_J = 125^\circ\text{C}$ | |
| V_F | Maximum Instantaneous Forward Voltage (Note 4) see Figure 2 $(i_F = 2.0 \text{ A})$ | 0.50 | 0.46 | V |
| | | | | |
| I_R | Maximum Instantaneous Reverse Current (Note 4) see Figure 4 $(V_R = 40 \text{ V})$ | 0.4 | 5.7 | mA |
| | | | | |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Mounted with minimum recommended pad size, PC Board FR4.
3. 1 inch square pad size (1 x 0.5 inch for each lead) on FR4 board.
4. Pulse Test: Pulse Width $\leq 250 \mu\text{s}$, Duty Cycle $\leq 2.0\%$.

TYPICAL CHARACTERISTICS

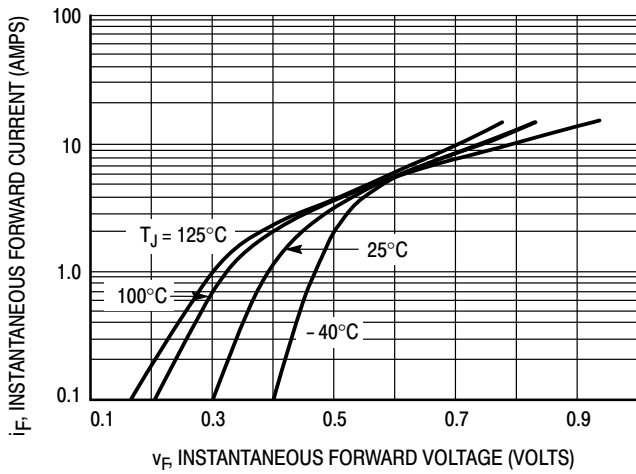


Figure 1. Typical Forward Voltage

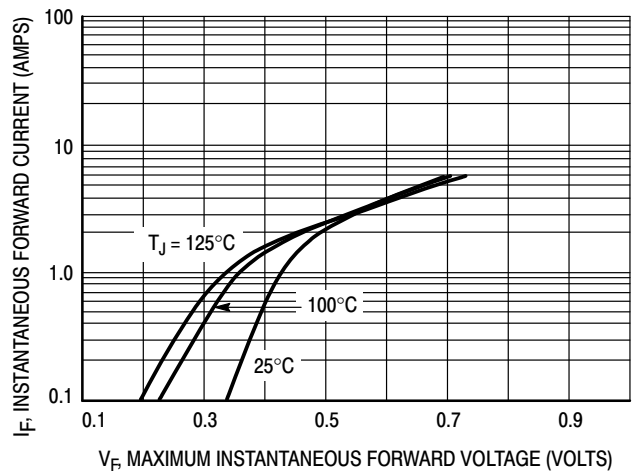


Figure 2. Maximum Forward Voltage

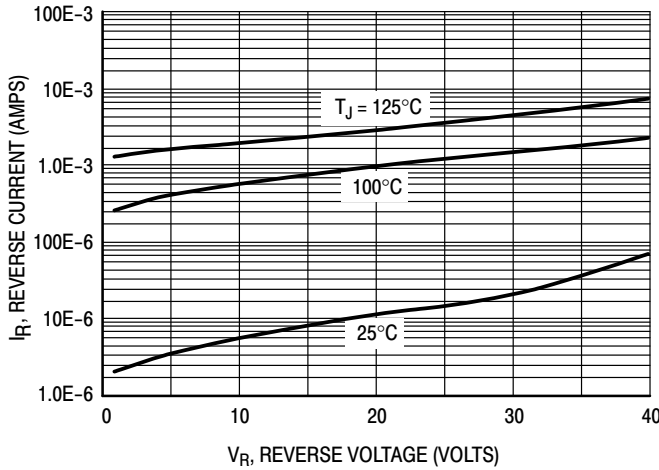


Figure 3. Typical Reverse Current

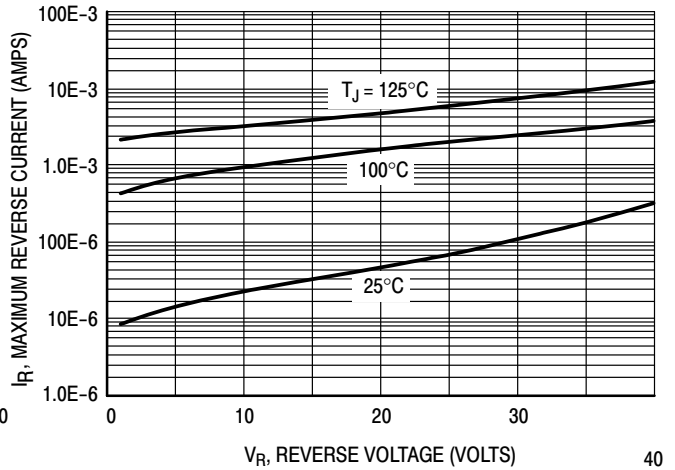


Figure 4. Maximum Reverse Current

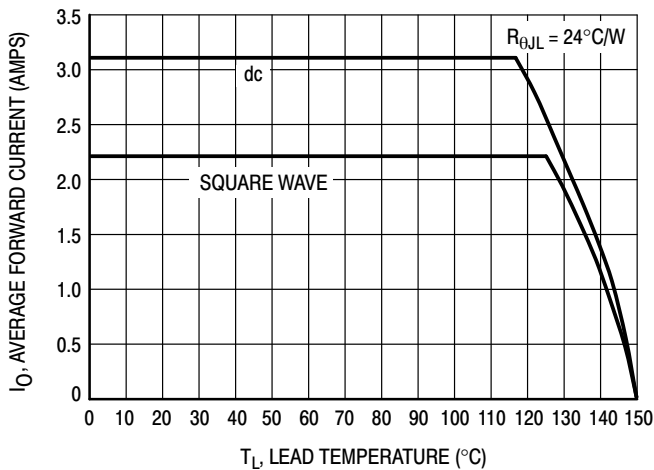


Figure 5. Current Derating

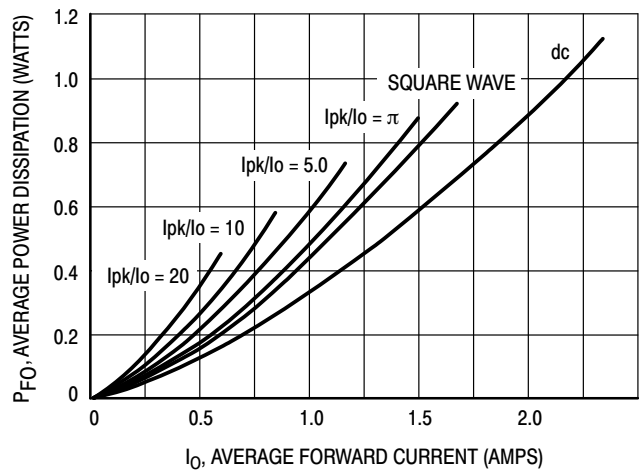


Figure 6. Forward Power Dissipation 2.5

SS22T3G, SS24T3G, NRVBSS24T3G, NRVBSS24NT3G

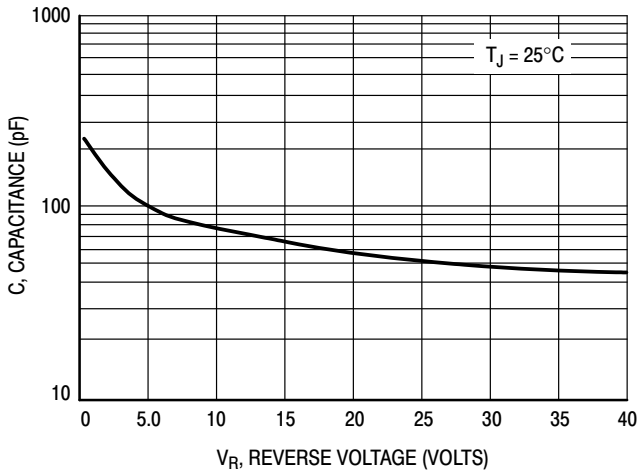


Figure 7. Capacitance

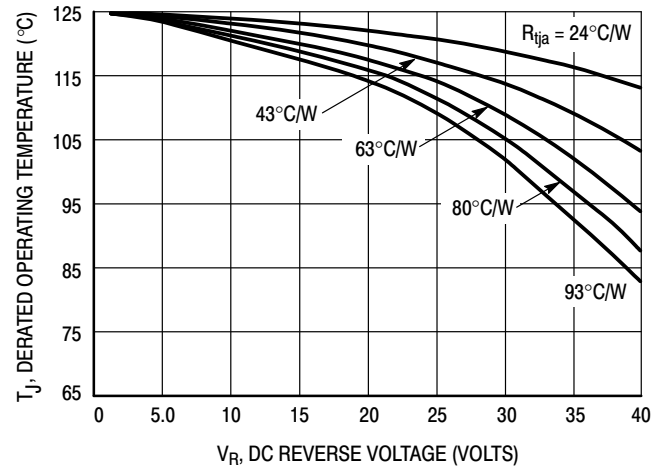


Figure 8. Typical Operating Temperature Derating*

* Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of T_J therefore must include forward and reverse power effects. The allowable operating T_J may be calculated from the equation:

$$T_J = T_{Jmax} - r(t)(P_f + P_r) \text{ where}$$

$r(t)$ = thermal impedance under given conditions,
 P_f = forward power dissipation, and
 P_r = reverse power dissipation

This graph displays the derated allowable T_J due to reverse bias under DC conditions only and is calculated as $T_J = T_{Jmax} - r(t)Pr$, where $r(t) = R_{thja}$. For other power applications further calculations must be performed.

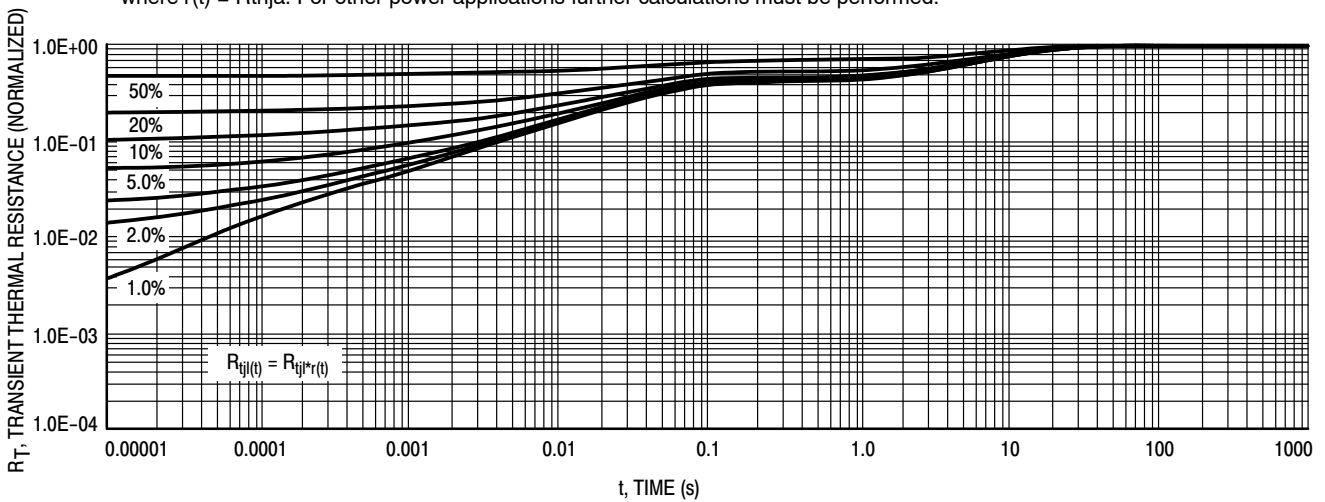


Figure 9. Thermal Response — Junction to Case

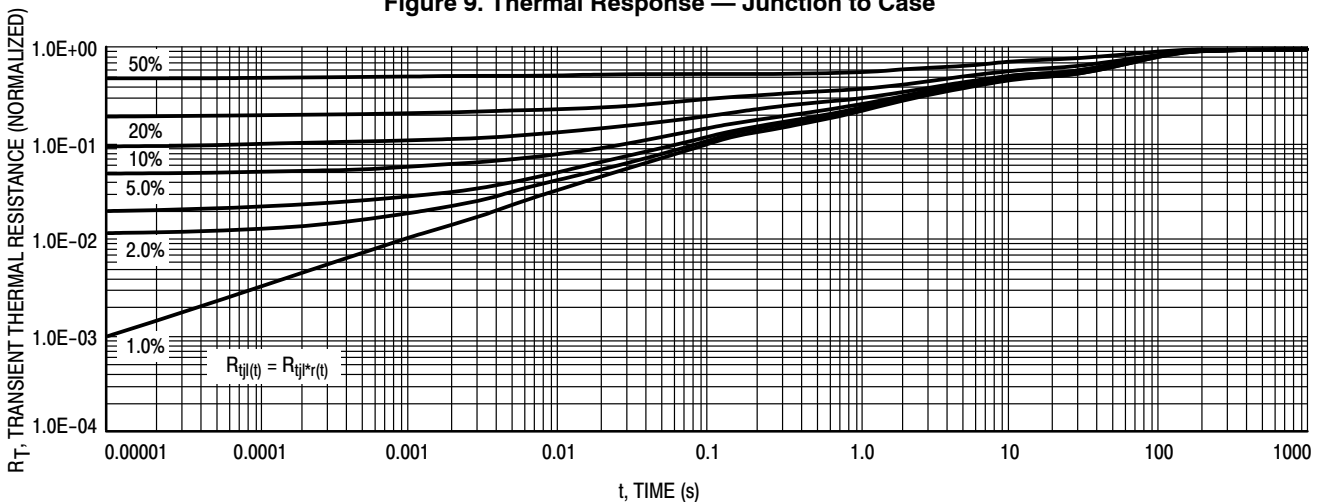


Figure 10. Thermal Response — Junction to Ambient

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®



SCALE 1:1

Polarity Band

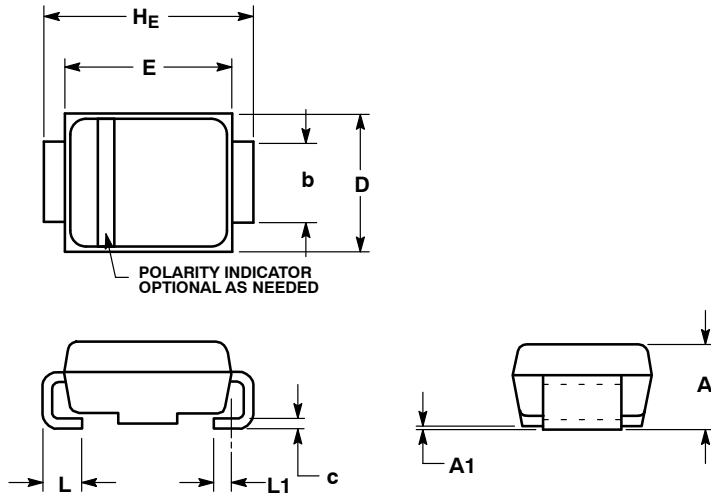


SCALE 1:1

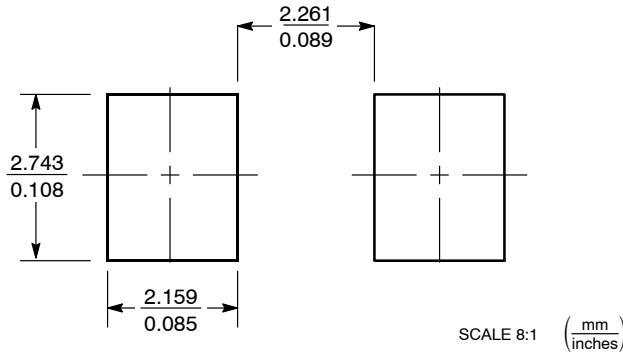
Non-Polarity Band

SMB
CASE 403A-03
ISSUE J

DATE 19 JUL 2012



SOLDERING FOOTPRINT*

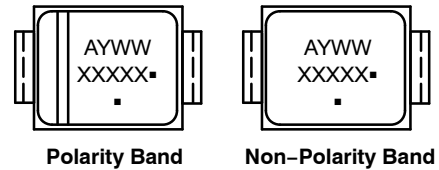


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

| DIM | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|-----------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 1.95 | 2.30 | 2.47 | 0.077 | 0.091 | 0.097 |
| A1 | 0.05 | 0.10 | 0.20 | 0.002 | 0.004 | 0.008 |
| b | 1.96 | 2.03 | 2.20 | 0.077 | 0.080 | 0.087 |
| c | 0.15 | 0.23 | 0.31 | 0.006 | 0.009 | 0.012 |
| D | 3.30 | 3.56 | 3.95 | 0.130 | 0.140 | 0.156 |
| E | 4.06 | 4.32 | 4.60 | 0.160 | 0.170 | 0.181 |
| HE | 5.21 | 5.44 | 5.60 | 0.205 | 0.214 | 0.220 |
| L | 0.76 | 1.02 | 1.60 | 0.030 | 0.040 | 0.063 |
| L1 | 0.51 REF | | | 0.020 REF | | |

GENERIC MARKING DIAGRAM*



- XXXXX = Specific Device Code
 - A = Assembly Location
 - Y = Year
 - WW = Work Week
 - = Pb-Free Package
- (Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

| | | |
|-------------------------|--------------------|--|
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| DESCRIPTION: | SMB | PAGE 1 OF 1 |

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